

Abstract

Hermetically Encapsulated Component And Waferscale Method For The Production
Thereof

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A component having a sandwich-like structure is described, in which the chip that carries the component structures is glued together with a frame structure and a diffusion-proof cover, in such a manner that the component structures are disposed in the interior of the structure and preferably in a cavity. The layer transitions of the structures are
10 protected, at the side edges, with a metallization. Interfacial connections through the cover connect contacts on the underside of the cover with the connector metallizations of the component structures on the chip. The interfacial connections are sealed with an underside metallization.

15 Figure 1